

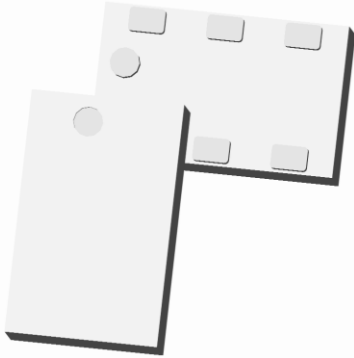


**THE DATASHEET OF
BD0826J50200AHF**



Xinger®

Ultra Low Profile 0805 Balun 50Ω to 200Ω Balanced



Description

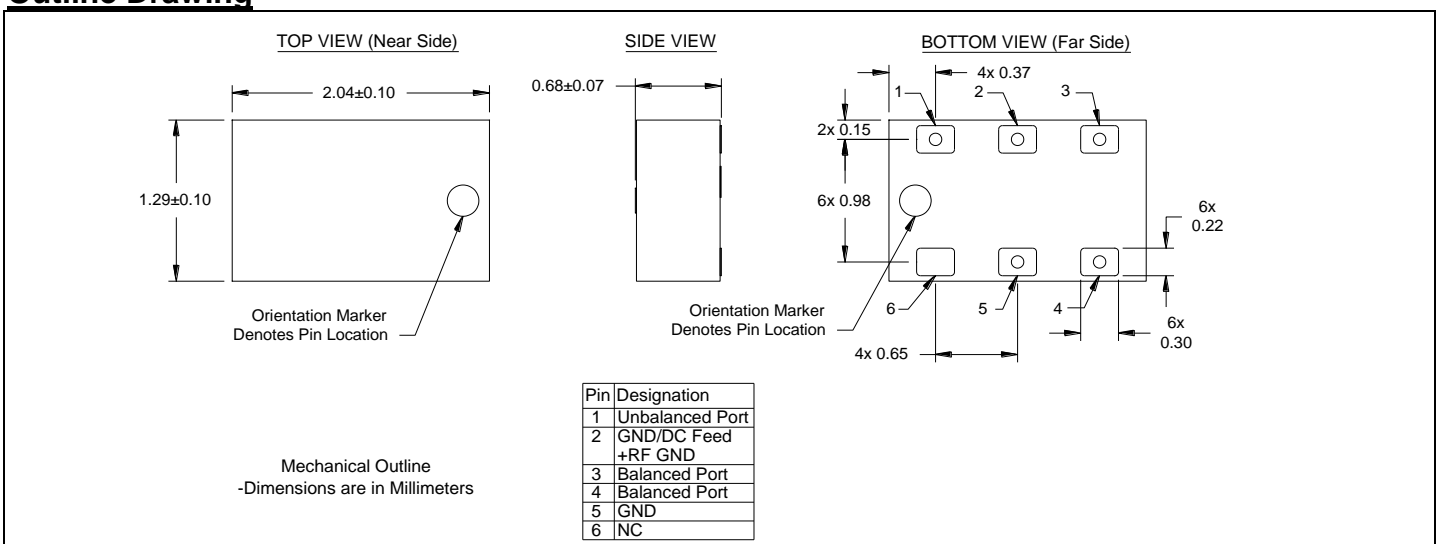
The BD0826J50200AHF is a low profile sub-miniature balanced to unbalanced transformer designed for differential inputs and output locations on next generation wireless chipsets in an easy to use surface mount package covering the GSM, DCS, PCS, UMTS, CDMA and 802.11 b+g+n frequencies. The BD0826J50200AHF is ideal for high volume manufacturing and is higher performance than traditional ceramic and lumped element baluns. The BD0826J50200AHF has an unbalanced port impedance of 50Ω and a 200Ω balanced port impedance. This transformation enables single ended signals to be applied to differential ports on modern integrated chipsets. The output ports have equal amplitude (-3dB) with 180 degree phase differential. The BD0826J50200AHF is available on tape and reel for pick and place high volume manufacturing.

Detailed Electrical Specifications: Specifications subject to change without notice.

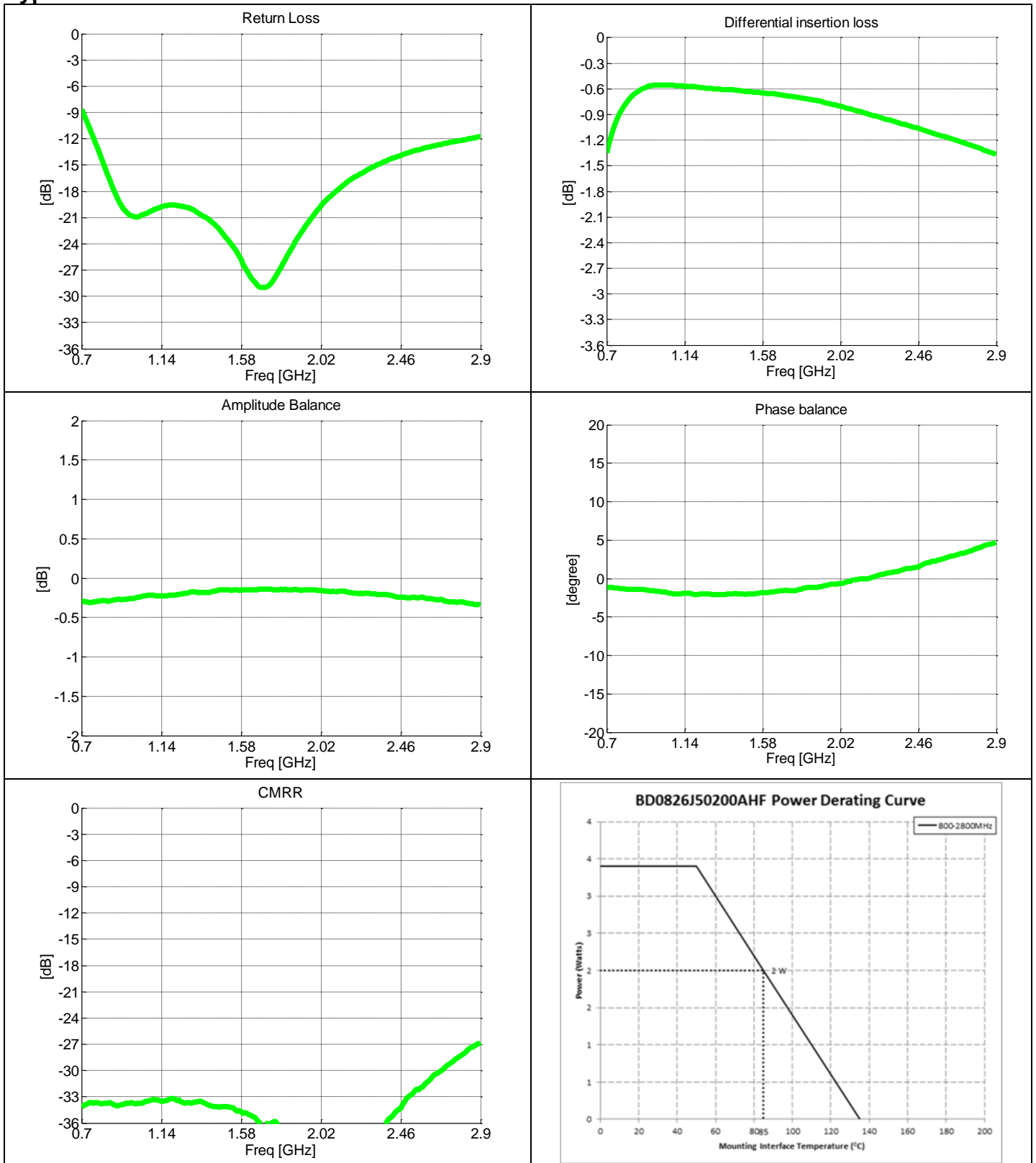
Features:	Parameter	ROOM (25°C)			ROOM (25°C)			Unit
		Min.	Typ.	Max	Min.	Typ.	Max	
• 800 – 2600 MHz	Frequency	800		2600	700		2800	MHz
• 700 – 2800 MHz	Unbalanced Port Impedance		50			50		Ω
• 0.7mm Height Profile	Balanced Port Impedance		200			200		Ω
• 50Ω to 2 x 100Ω	Return Loss	8.5	13		8.0	9		dB
• GSM/DCS/PCS/UMTS/CDMA	Insertion Loss*		1.2	1.5		1.5	1.6	dB
• Low Insertion Loss	Amplitude Balance		0.4	1.3		0.4	1.3	dB
• Input to Output DC Isolation	Phase Balance		3	7		4	8	Degrees
• Surface Mountable	CMRR		30			25		dB
• Tape & Reel	Power Handling @85C			2			2	Watts
• Non-conductive Surface	Operating Temperature	-55		+105	-55		+105	°C
• RoHS Compliant								
• Halogen Free								

* Insertion Loss stated at room temperature (Insertion Loss is approximately 0.1 dB higher at +85 °C)

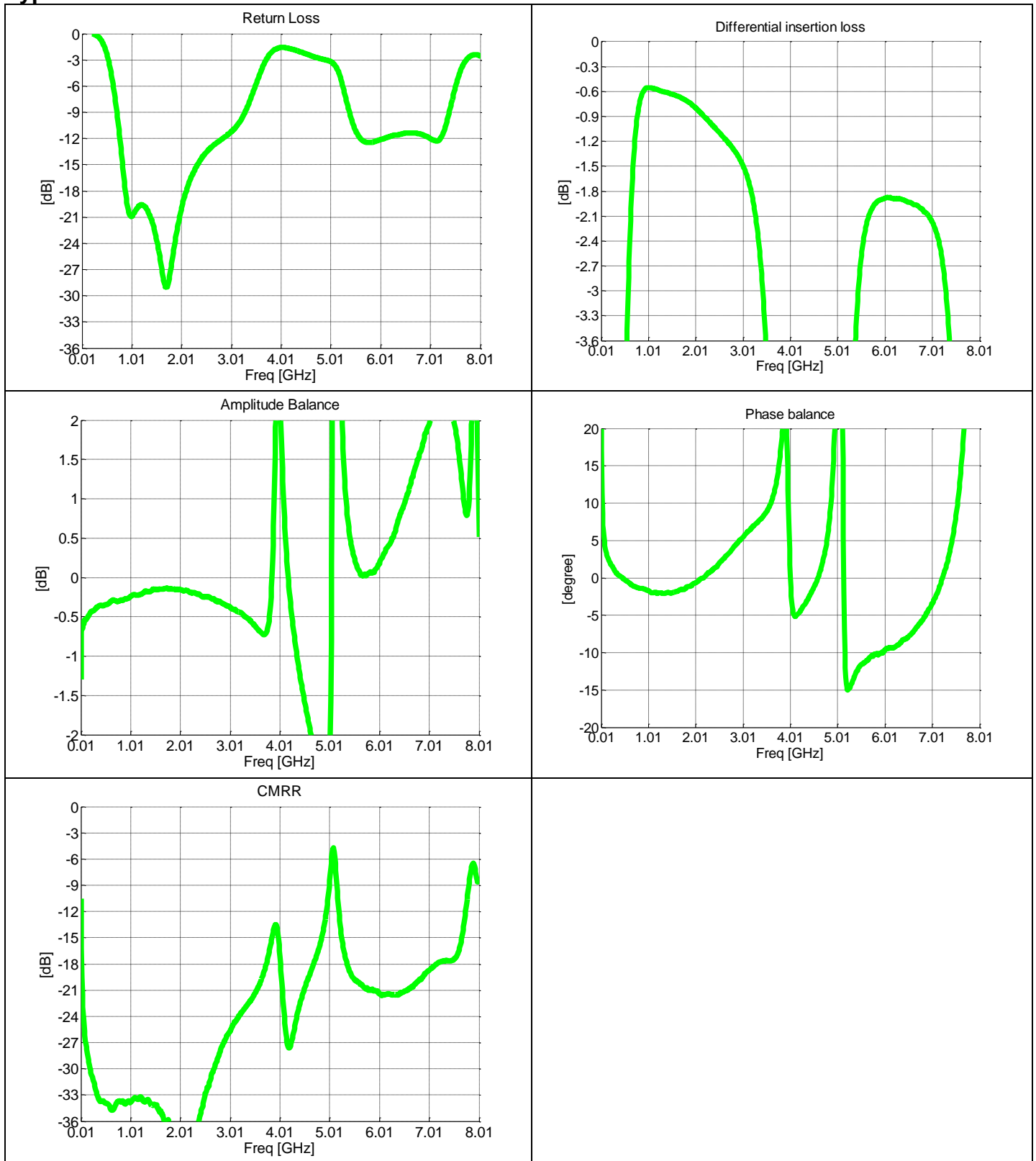
Outline Drawing



Typical Performance: 700 MHz to 2900 MHz



Typical Broadband Performance: 10 MHz to 8010 MHz



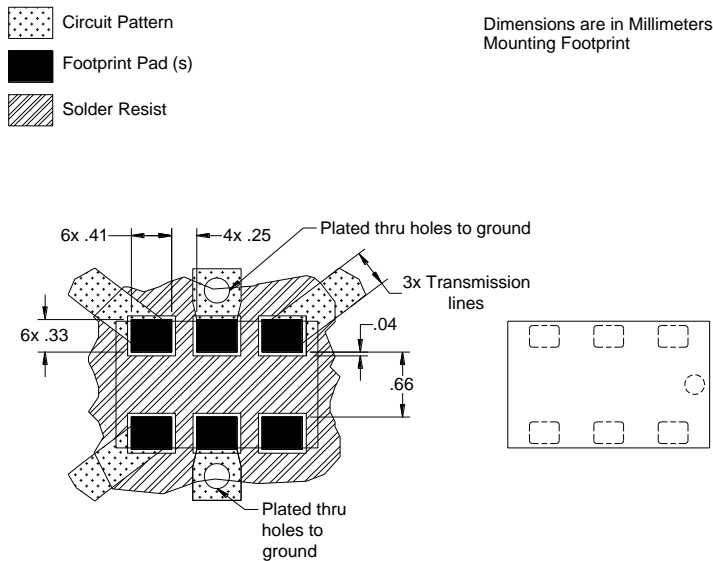
Mounting Configuration:

In order for Xinger surface mount components to work optimally, the proper impedance transmission lines must be used to connect to the RF ports. If this condition is not satisfied, insertion loss, Isolation and VSWR may not meet published specifications.

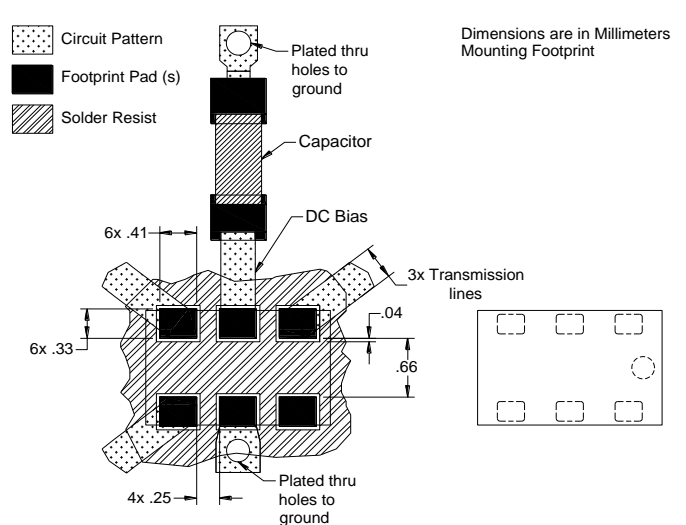
All of the Xinger components are constructed from organic PTFE based composites which possess excellent electrical and mechanical stability. Xinger components are compliant to a variety of ROHS and Green standards and ready for Pb-free soldering processes. Pads are Gold plated with a Nickel barrier.

An example of the PCB footprint used in the testing of these parts is shown below. An example of a DC-biased footprint is also shown below. In specific designs, the transmission line widths need to be adjusted to the unique dielectric coefficients and thicknesses as well as varying pick and place equipment tolerances.

No Bias Footprint

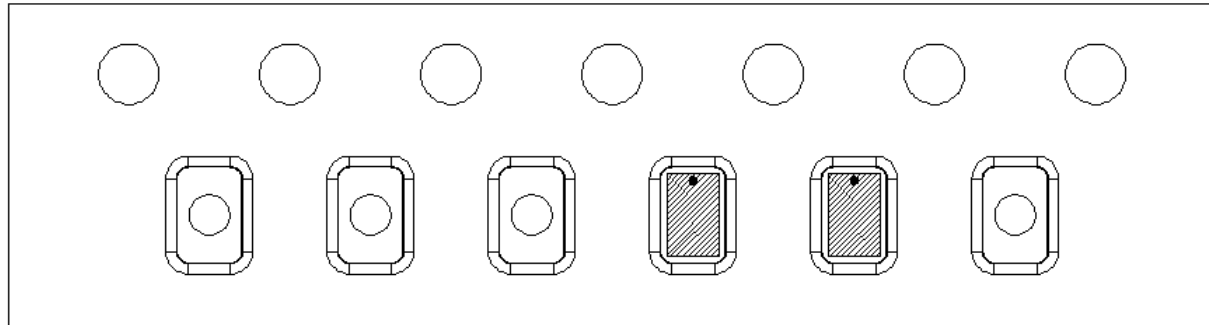


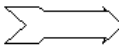
DC Bias Footprint



Packaging and Ordering Information

Parts are available in reel and are packaged per EIA 481-D. Parts are oriented in tape and reel as shown below. Minimum order quantities are 10,000 per reel.



Direction of
Part Feed
(Unloading) 

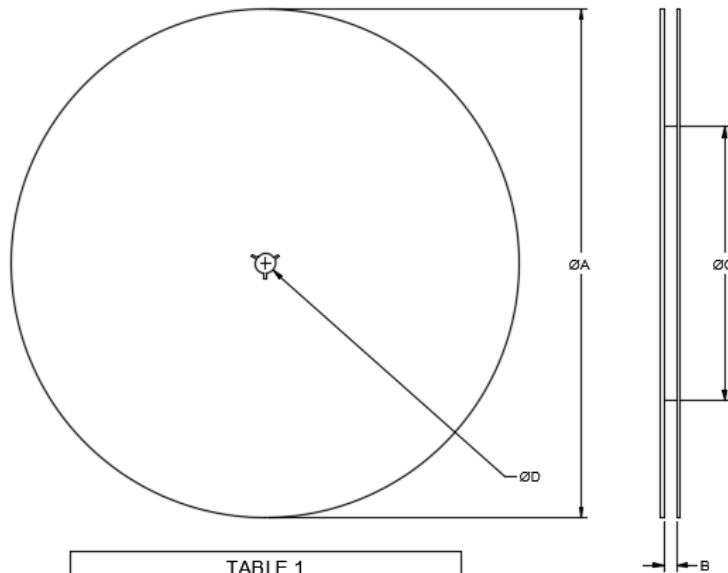


TABLE 1	
REEL DIMENSIONS (inches [mm])	
ØA	13.0 [330.0]
B	.315 [8.0]
ØC	7.0 [177.8]
ØD	.512 [13.0]